

# STARPOWER

SEMICONDUCTOR™

# IGBT

## GD200MLT60C2S

**Molding Type Module****600V/200A 3-level in one-package**

### General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as 3-level-applications.



### Features

- Low  $V_{CE(sat)}$  trench IGBT technology
- 5 $\mu$ s short circuit capability
- $V_{CE(sat)}$  with positive temperature coefficient
- Maximum junction temperature 175 °C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

### Typical Applications

- Solar power
- UPS
- 3-Level-Applications

**IGBT T1 T2 T3 T4**  $T_C=25^\circ\text{C}$  unless otherwise noted**Maximum Rated Values**

Symbol	Description	GD200MLT60C2S	Units
$V_{CES}$	Collector-Emitter Voltage @ $T_j=25^\circ\text{C}$	600	V
$V_{GES}$	Gate-Emitter Voltage @ $T_j=25^\circ\text{C}$	$\pm 20$	V
$I_C$	Collector Current @ $T_C=25^\circ\text{C}$ @ $T_C=80^\circ\text{C}$	265 200	A
$I_{CM}$	Pulsed Collector Current $t_p=1\text{ms}$	400	A
$P_{tot}$	Total Power Dissipation @ $T_j=175^\circ\text{C}$	644	W

**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$T_j=25^\circ\text{C}$	600			V
$I_{CES}$	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V},$ $T_j=25^\circ\text{C}$			5.0	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V},$ $T_j=25^\circ\text{C}$			400	nA

**On Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=2.0\text{mA}, V_{CE}=V_{GE},$ $T_j=25^\circ\text{C}$	4.0	4.4	6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=200\text{A}, V_{GE}=15\text{V},$ $T_j=25^\circ\text{C}$		1.65	2.10	V
		$I_C=200\text{A}, V_{GE}=15\text{V},$ $T_j=175^\circ\text{C}$		2.00		

**Switching Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300V, I_C=200A,$ $R_G=2.4\Omega, V_{GE}=\pm 15V,$ $T_j=25^\circ C$		136		ns
$t_r$	Rise Time			54		ns
$t_{d(off)}$	Turn-Off Delay Time			122		ns
$t_f$	Fall Time			87		ns
$E_{on}$	Turn-On Switching Loss			1.79		mJ
$E_{off}$	Turn-Off Switching Loss			1.99		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300V, I_C=200A,$ $R_G=2.4\Omega, V_{GE}=\pm 15V,$ $T_j=125^\circ C$		145		ns
$t_r$	Rise Time			70		ns
$t_{d(off)}$	Turn-Off Delay Time			170		ns
$t_f$	Fall Time			112		ns
$E_{on}$	Turn-On Switching Loss			3.06		mJ
$E_{off}$	Turn-Off Switching Loss			3.62		mJ
$C_{ies}$	Input Capacitance	$V_{CE}=30V, f=1Mhz,$ $V_{GE}=0V$		15.4		nF
$C_{oes}$	Output Capacitance			1.06		nF
$C_{res}$	Reverse Transfer Capacitance			0.46		nF
$Q_G$	Gate Charge	$V_{CC}=400V, I_C=200A,$ $V_{GE}=15V$		417		nC
$R_{Gint}$	Internal Gate Resister			2.5		$\Omega$
$I_{SC}$	SC Data	$t_p \leq 5\mu s, V_{GE}=15V,$ $T_j=125^\circ C, V_{CC}=360V,$ $V_{CEM} \leq 600V$		1800		A

**DIODE D1 D2 D3 D4**  $T_C=25^\circ\text{C}$  unless otherwise noted**Maximum Rated Values**

Symbol	Description	GD200MLT60C2S	Units
$V_{RRM}$	Repetitive Peak Reverse Voltage @ $T_j=25^\circ\text{C}$	600	V
$I_F$	DC Forward Current $T_C=80^\circ\text{C}$	200	A
$I_{FRM}$	Repetitive Peak Forward Current $t_p=1\text{ms}$	400	A

**Characteristics Values**

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=200\text{A}$ , $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$		1.40	1.80	V
			$T_j=125^\circ\text{C}$		1.40		
$Q_r$	Recovered Charge	$I_F=200\text{A}$ , $V_R=300\text{V}$ , $R_G=2.4\Omega$ , $V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		9.6		$\mu\text{C}$
			$T_j=125^\circ\text{C}$		13.0		
$I_{RM}$	Peak Reverse Recovery Current	$V_R=300\text{V}$ , $R_G=2.4\Omega$ , $V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		120		A
			$T_j=125^\circ\text{C}$		157		
$E_{rec}$	Reverse Recovery Energy	$V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		1.88		mJ
			$T_j=125^\circ\text{C}$		3.62		

**DIODE D5 D6**  $T_C=25^\circ\text{C}$  unless otherwise noted**Maximum Rated Values**

Symbol	Description	GD200MLT60C2S	Units
$V_{RRM}$	Repetitive Peak Reverse Voltage @ $T_j=25^\circ\text{C}$	600	V
$I_F$	DC Forward Current $T_C=80^\circ\text{C}$	200	A
$I_{FRM}$	Repetitive Peak Forward Current $t_p=1\text{ms}$	400	A

**Characteristics Values**

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=200\text{A}$ , $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$		1.40	1.80	V
			$T_j=125^\circ\text{C}$		1.40		
$Q_r$	Recovered Charge	$I_F=200\text{A}$ , $V_R=300\text{V}$ , $R_G=2.4\Omega$ , $V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		9.6		$\mu\text{C}$
			$T_j=125^\circ\text{C}$		13.0		
$I_{RM}$	Peak Reverse Recovery Current	$V_R=300\text{V}$ , $R_G=2.4\Omega$ , $V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		120		A
			$T_j=125^\circ\text{C}$		157		
$E_{rec}$	Reverse Recovery Energy	$V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		1.88		mJ
			$T_j=125^\circ\text{C}$		3.62		

**NTC**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$R_{25}$	Rated Resistance			5.0		$k\Omega$
$\Delta R/R$	Deviation of $R_{100}$	$T_C=100^\circ\text{C}, R_{100}=493.3\Omega$	-5		5	%
$P_{25}$	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15K))]$		3375		K

## IGBT Module

Symbol	Parameter	Min.	Typ.	Max.	Units
$V_{ISO}$	Isolation Voltage RMS, $f=50\text{Hz}, t=1\text{min}$		2500		V
$R_{\theta JC}$	Junction-to-Case (per IGBT T1 T2 T3 T4)			0.233	K/W
	Junction-to-Case (per DIODE D1 D2 D3 D4)			0.366	
	Junction-to-Case (per DIODE D5 D6)			0.406	
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)		0.035		K/W
$T_{jmax}$	Maximum Junction Temperature			175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-40		125	$^\circ\text{C}$
Mounting Torque	Power Terminal Screw:M6 Mounting Screw:M6	2.5 3.0		5.0 5.0	N.m
Weight	Weight of Module		340		g

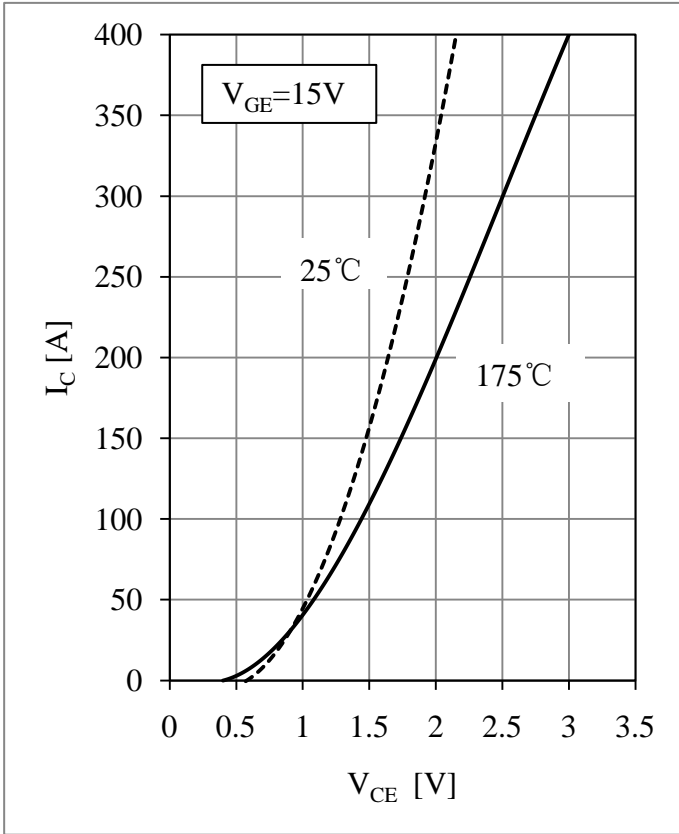


Fig 1. IGBT T1-T4 Output Characteristic

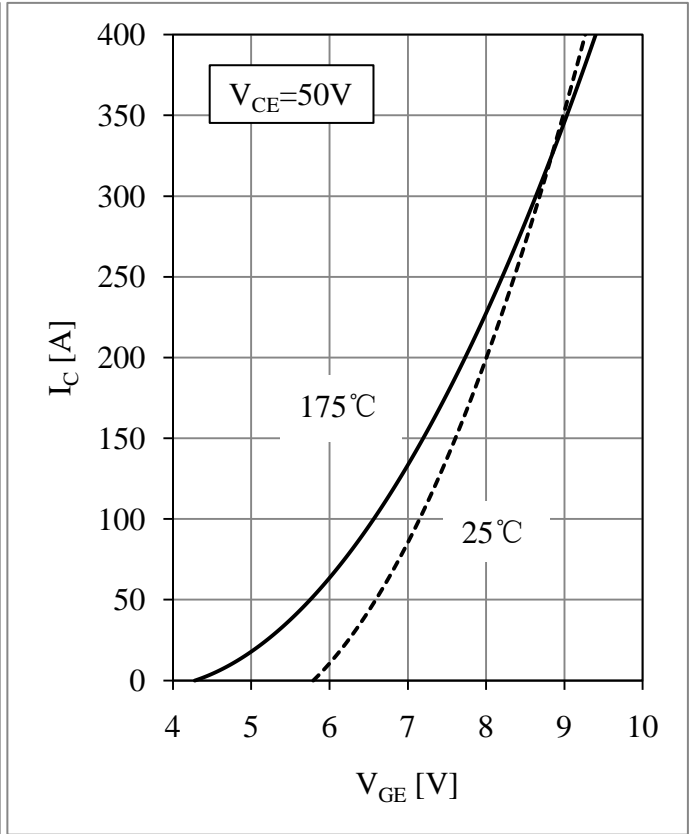


Fig 2. IGBT T1-T4 Transfer Characteristic

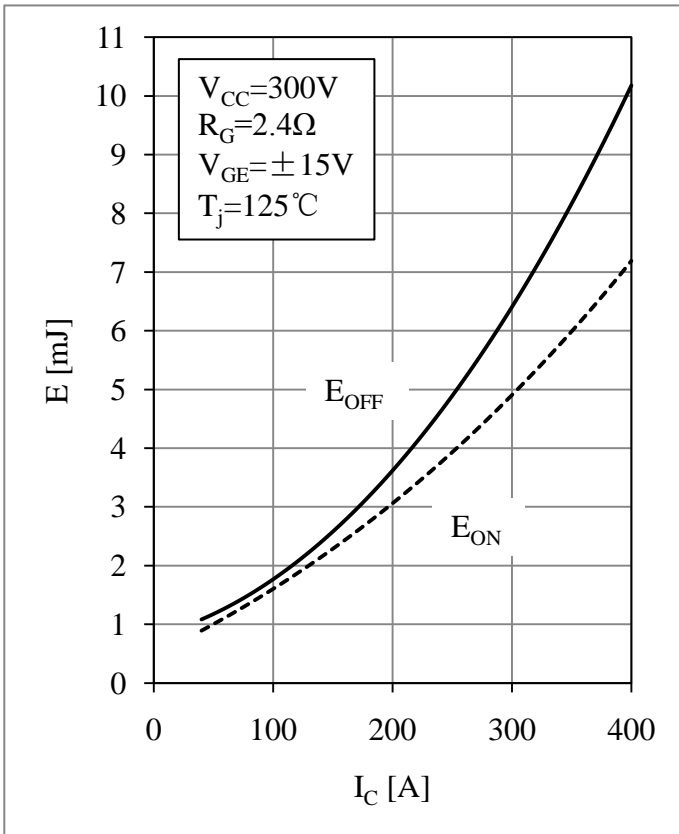


Fig 3. IGBT T1-T4 Switching Loss vs.  $I_C$

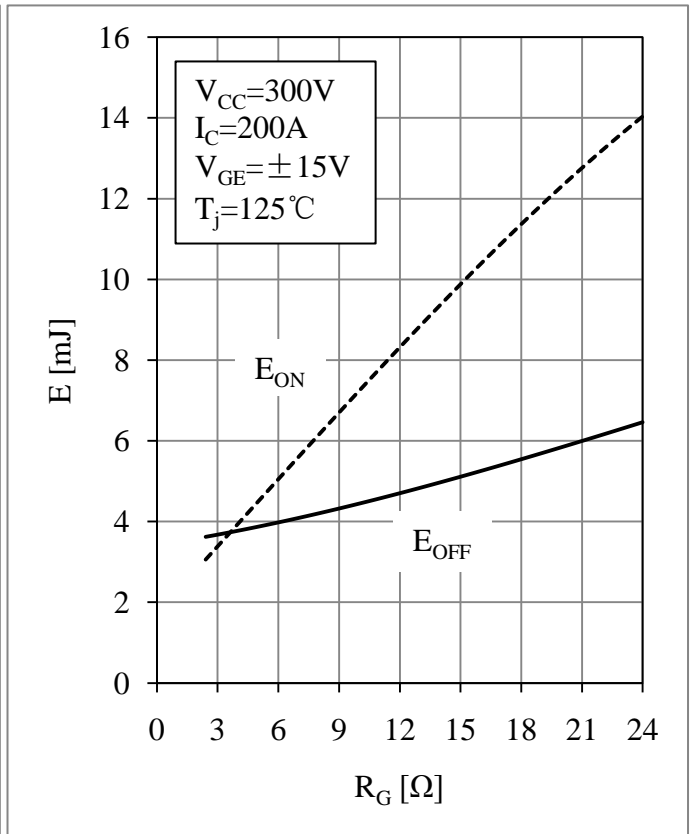


Fig 4. IGBT T1-T4 Switching Loss vs.  $R_G$

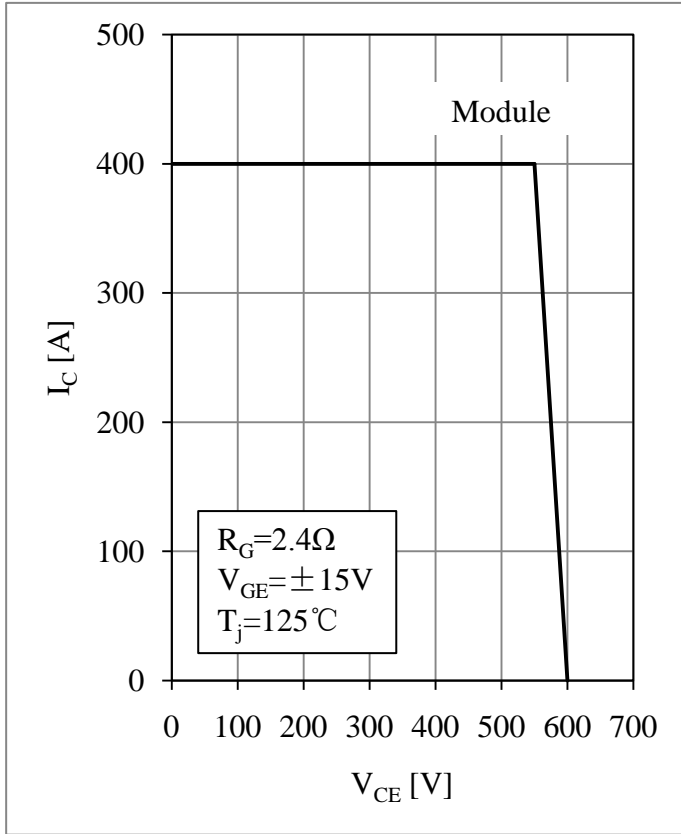


Fig 5. IGBT T1-T4 RBSOA

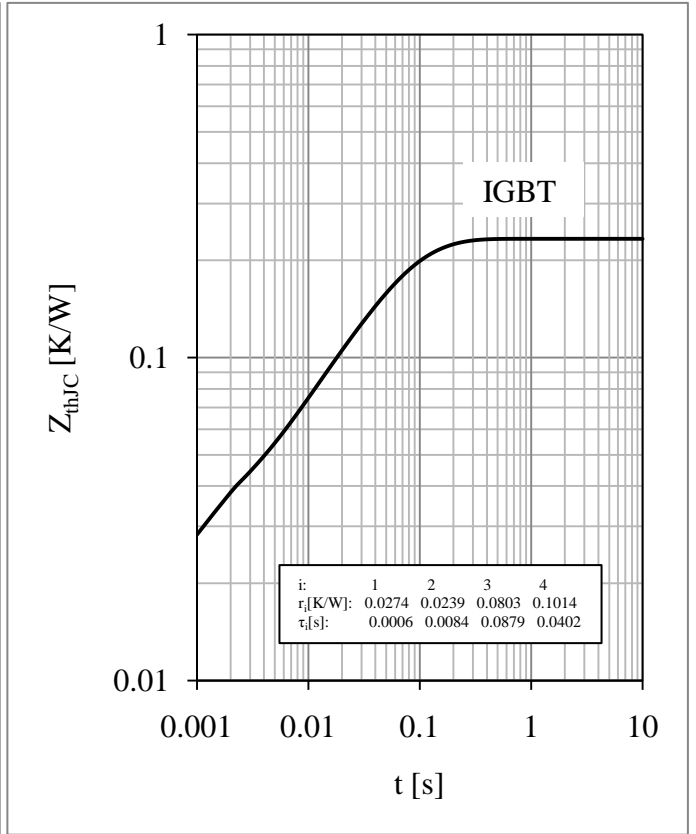


Fig 6. IGBT T1-T4 Transient Thermal Impedance

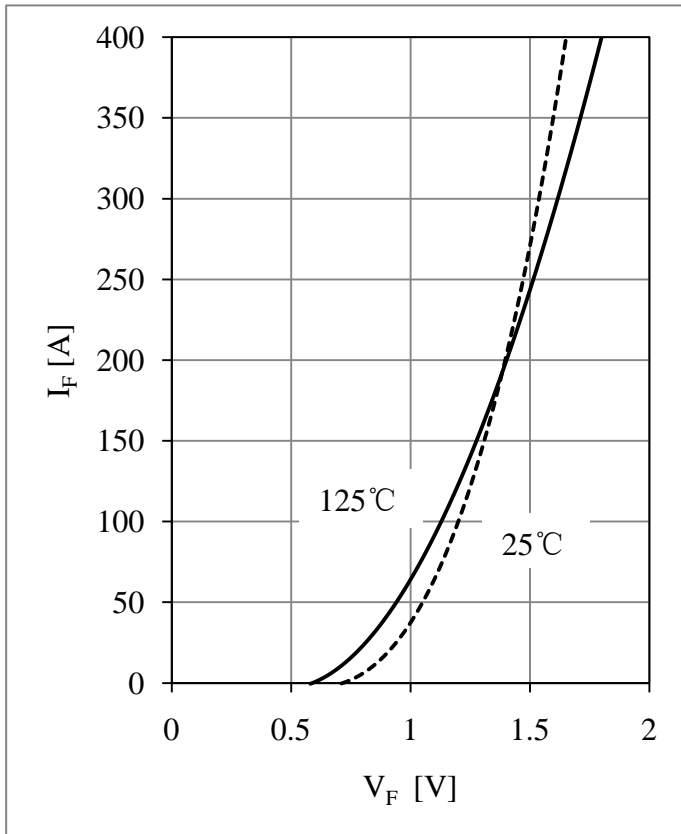


Fig 7. Diode D1-D4 Forward Characteristic

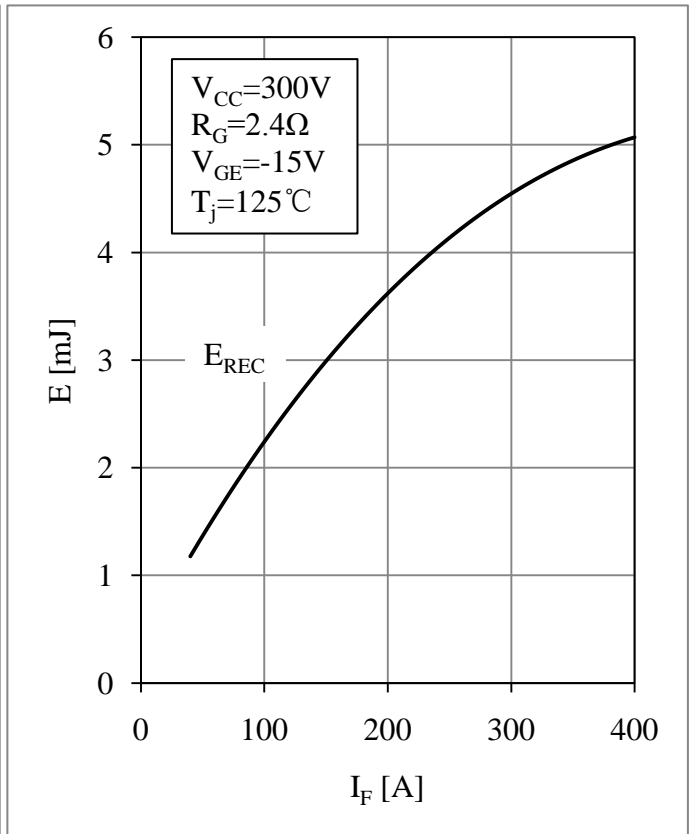


Fig 8. Diode D1-D4 Switching Loss vs.  $I_F$

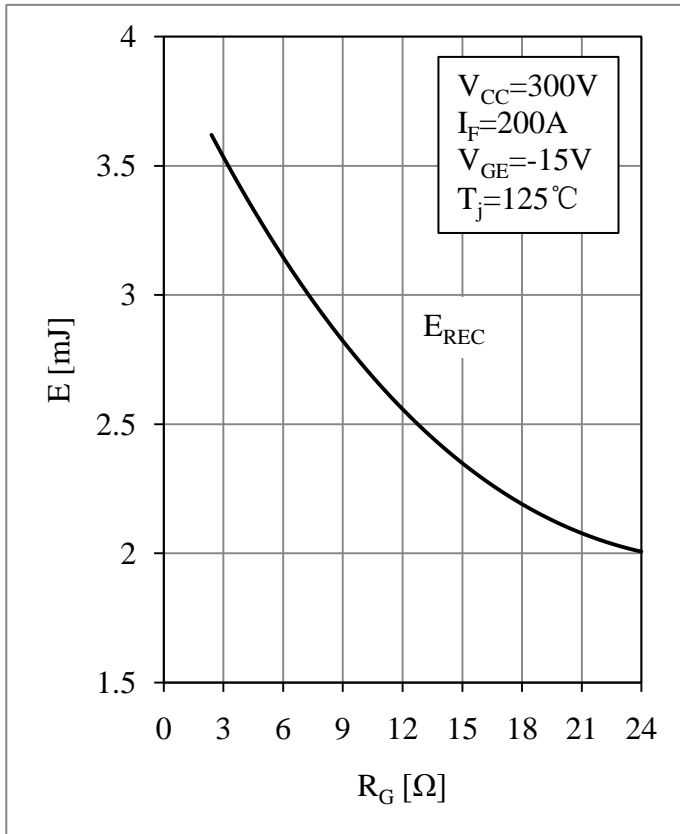


Fig 9. Diode D1-D4 Switching Loss vs.  $R_G$

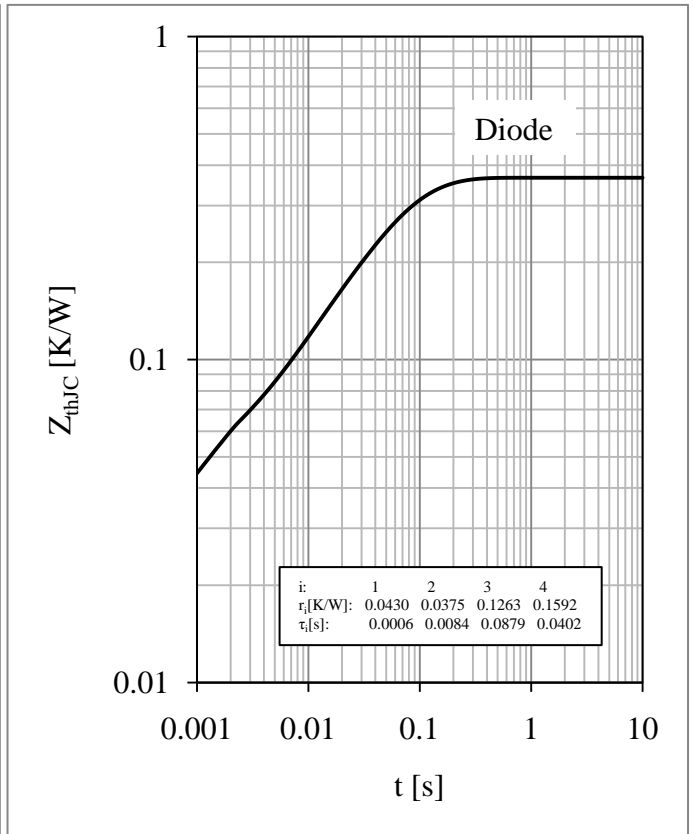


Fig 10. Diode D1-D4 Transient Thermal Impedance

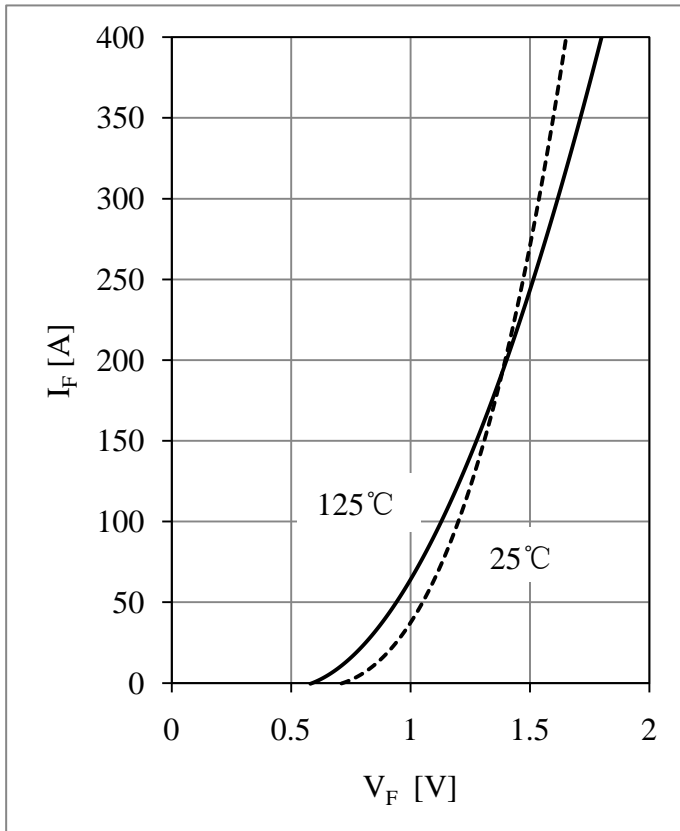


Fig 11. Diode D5-D6 Forward Characteristic

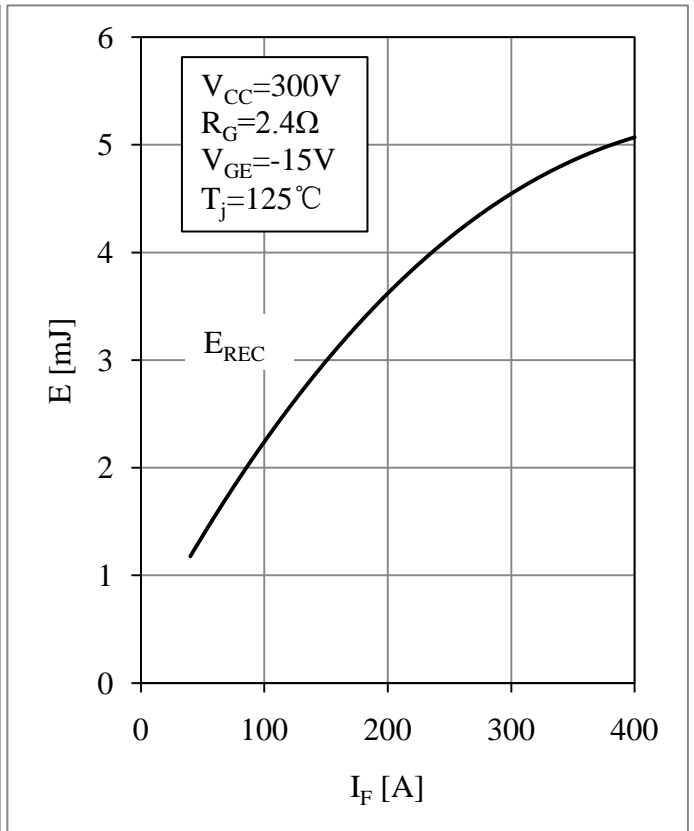


Fig 12. Diode D5-D6 Switching Loss vs.  $I_F$



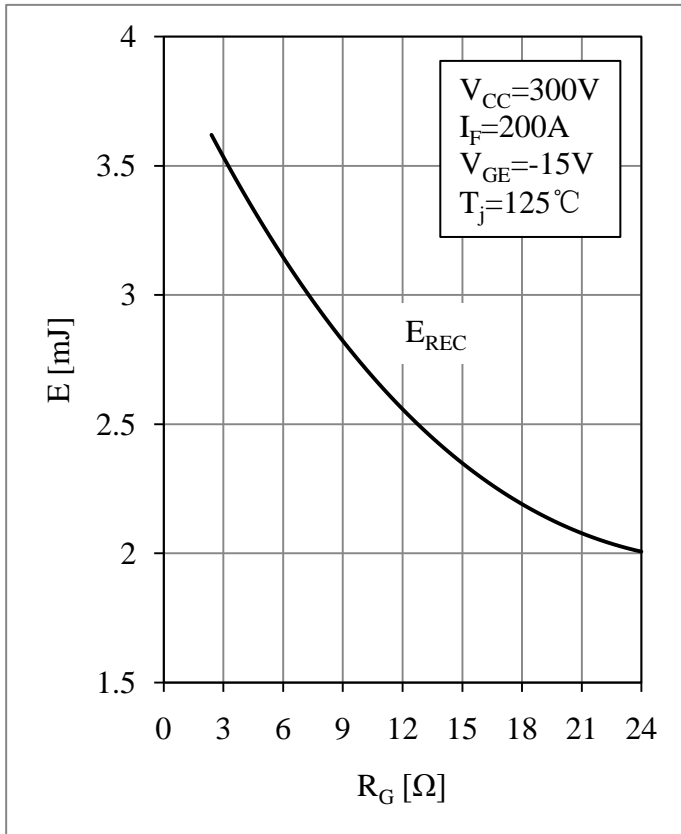


Fig 13. Diode D5-D6 Switching Loss vs.  $R_G$

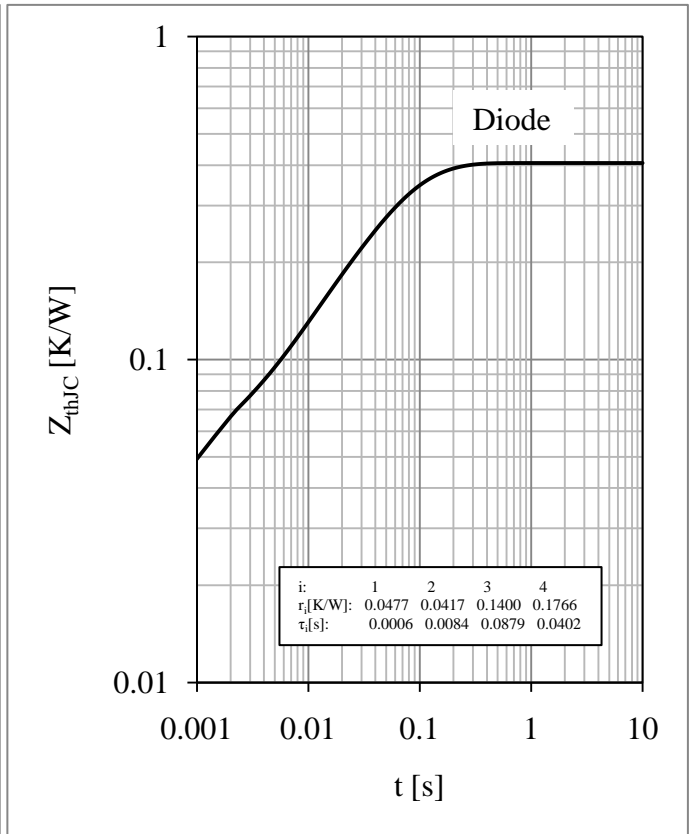


Fig 14. Diode D5-D6 Transient Thermal Impedance

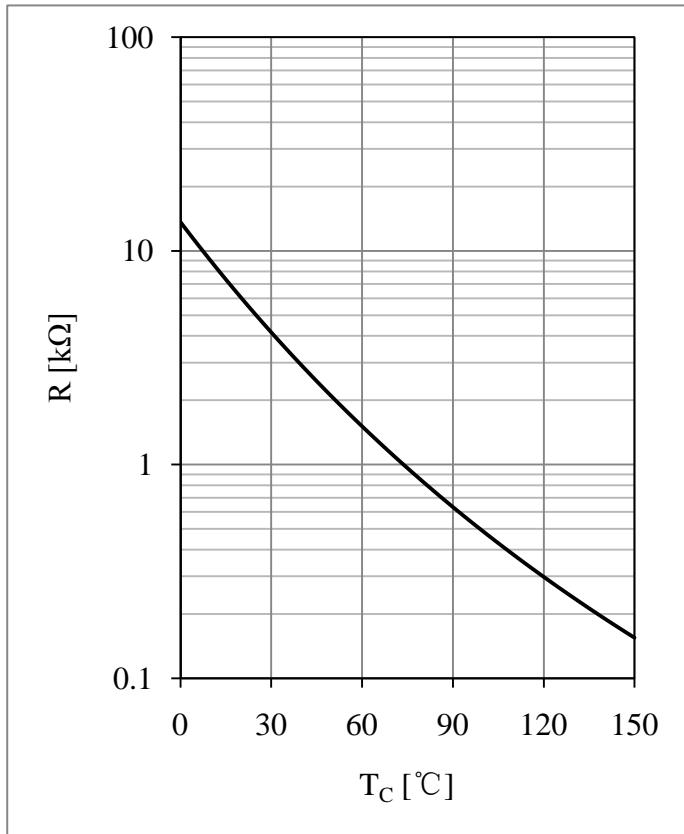
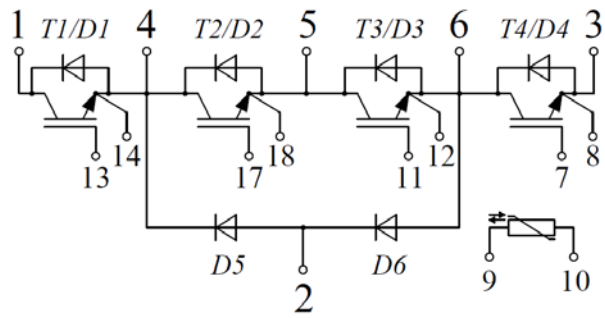


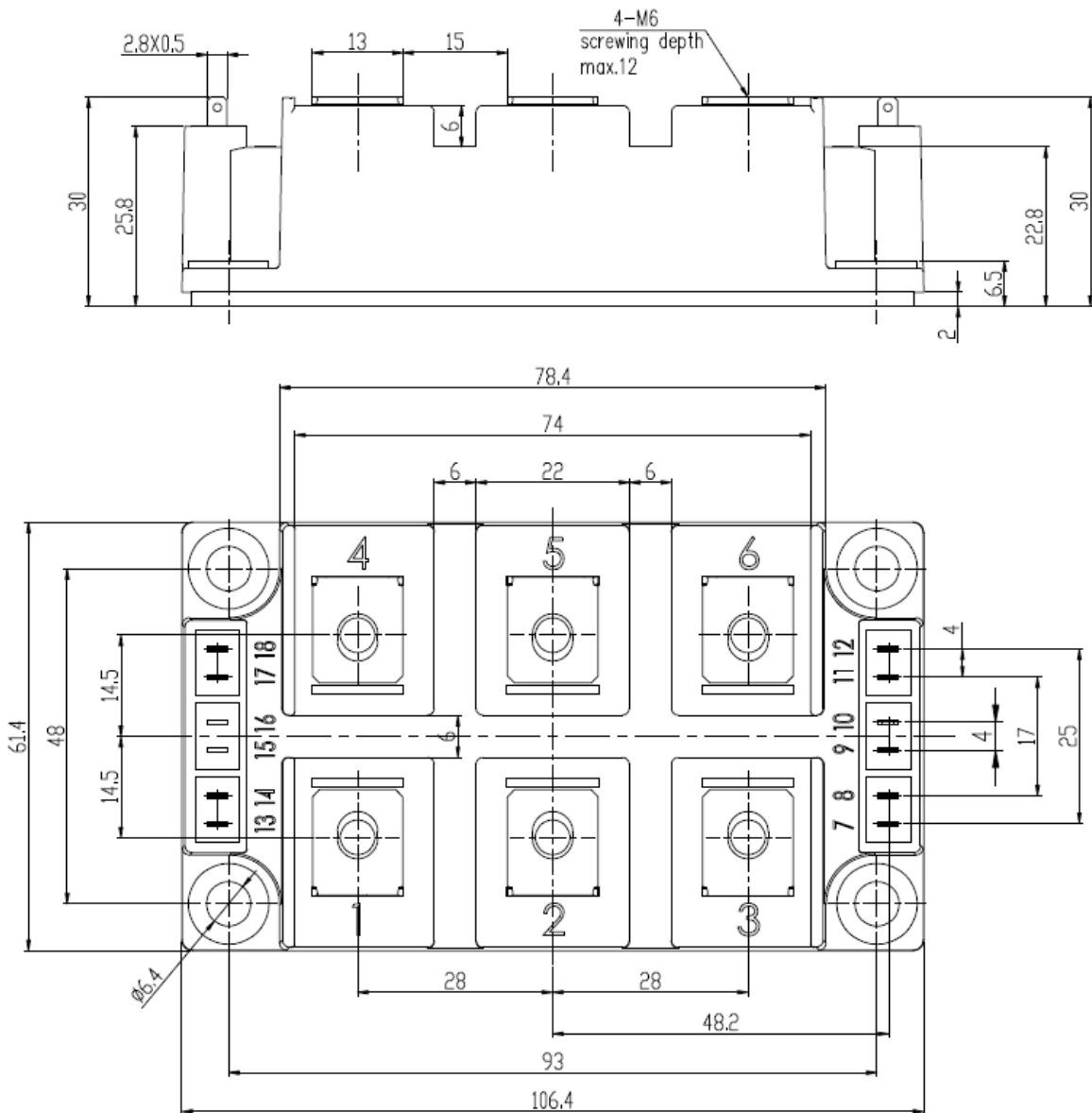
Fig 15. NTC Temperature Characteristic

### Equivalent Circuit Schematic



### Package Dimensions

Dimensions in Millimeters



## Terms and Conditions of Usage

The data contained in this product datasheet is exclusively intended for technically trained staff. you and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see [www.powersemi.cc](http://www.powersemi.cc)), For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify.

If and to the extent necessary, please forward equivalent notices to your customers.  
Changes of this product data sheet are reserved.